# ATLAS ITk Lecce Update

### G. Chiodini - INFN Lecce

Oct 14, 2021

## Local support FDR (Final Design Review)

leri ed oggi ci sono le presentazioni del Local Support FDR per Outer Barrel e Outer Endcap: <u>https://indico.cern.ch/event/1075990/</u>

Presentazione interessante di Review per i local support dell'Outer Encap:

- Endcap Half Ring Design and Interfaces - Peter Sutcliffe (University of Liverpool (GB))

- OE Bare Local Supports Qualification: Material and Electrical (G&S) Francisca Munoz Sanchez (University of Manchester (GB))

NB: Mi hanno chiesto i nomi sul documento di Local Support FDR per l'Outer Barrel ed io ho comunicato II mio, quello di Alessandro (handling frame) e quello di Rita (transport box). Ovviamente sul Loaded Local Support FDR ci sarà il nome di tutto ITK Lecce (Prossima slide).

## Local support FDR from Cecilia

- End-cap local supports are fabricated in two independent lines, one in Italy and one in UK.
  - The Italian line will produce 50% of Layer 2 and all Layer 4 Half rings.
  - The UK line will produce 50% of Layer 2 and all Layer 3 Half rings. This is mainly based on machining facilities.
- In the latest ITk schedule, production of Layer 2 HR will happen from November 2022 to September 2023. Layer 4 (IT) and Layer 3 (UK) HR will be produced from September 2023 to December 2024.

#### Number Bare Half Ring depends on the number of Loaded local supports needed:

| Sub-system | Needed<br>for detector | Production<br>(includes yield) | Pre-production | Total<br>to produce |
|------------|------------------------|--------------------------------|----------------|---------------------|
| Endcap A   | 56                     | 58                             | 4              | 62                  |
| Endcap C   | 56                     | 58                             | 4              | 62                  |

Required loaded local supports

| Sub-system | Needed | Production<br>(includes yield) | <b>Pre-production</b> | Total<br>to produce |
|------------|--------|--------------------------------|-----------------------|---------------------|
| Endcap A   | 62     | 68                             | 4                     | 72                  |
| Endcap C   | 62     | 68                             | 4                     | 72                  |

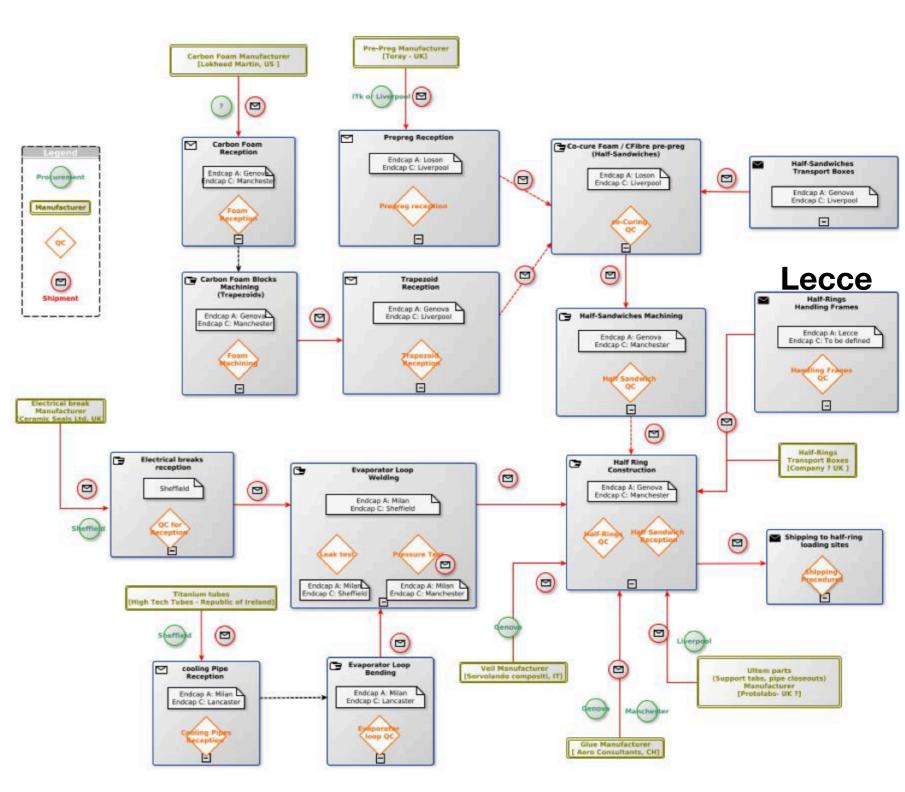
Required bare local supports

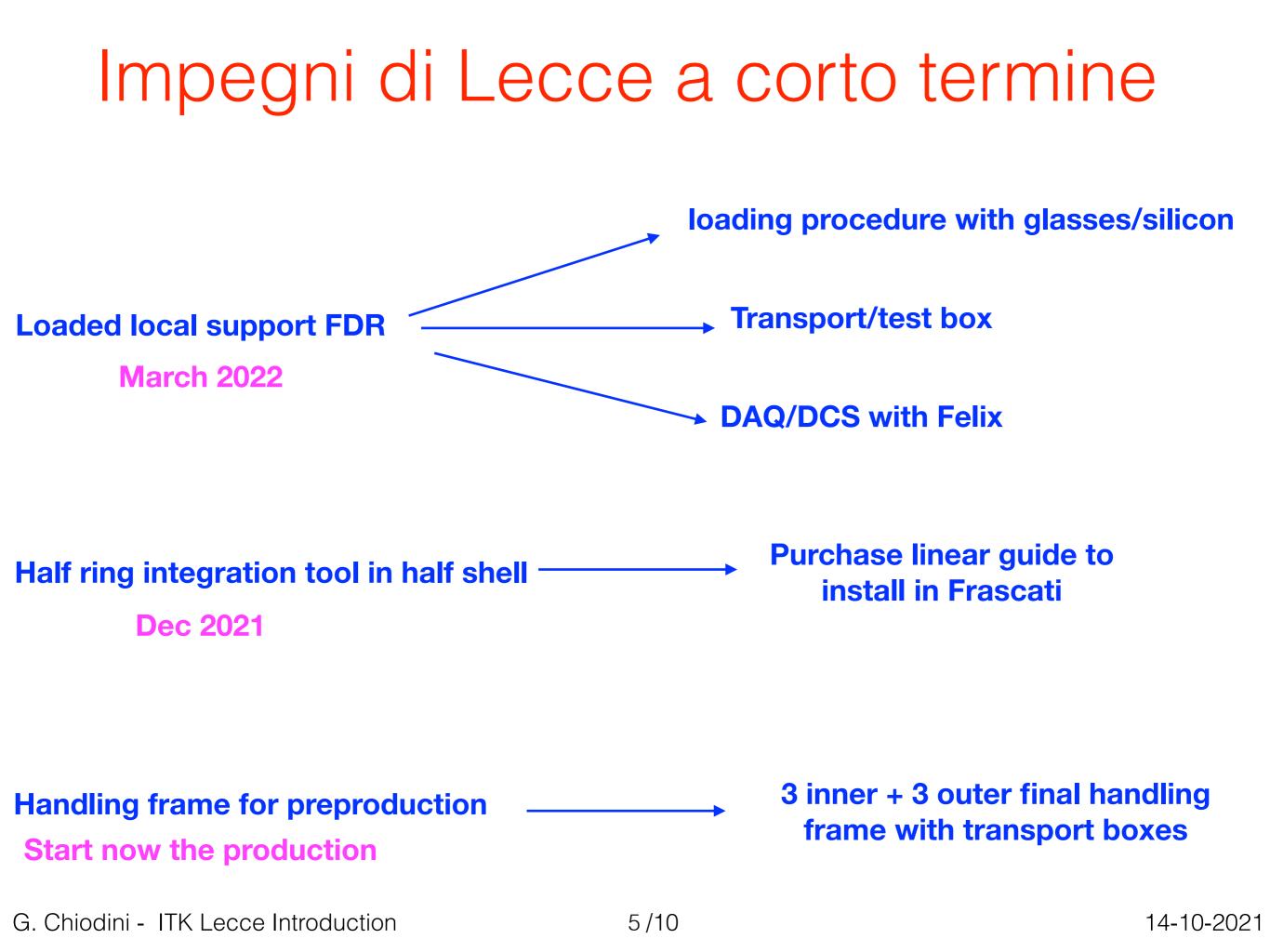
#### G. Chiodini - ITK Lecce Introduction

### Production flow diagram illustrates sequential steps of LS fabrication procedure.

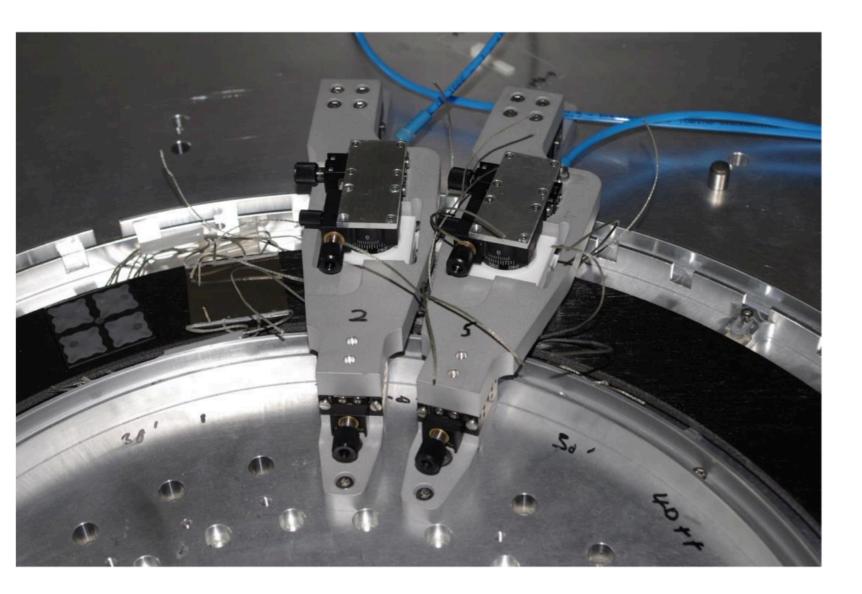
- Shipments and QC procedures are explicitly indicated.
- The exact place where the manufacturing or testing is performed is also indicated.
- Identical production flow.

Only relevant difference is cocuring of the HS: Italy → External company (Loson), UK → University lab (Liverpool).





# Four loading sites: RAL



Gantry X,Y,Z

**No Theta Stage** 

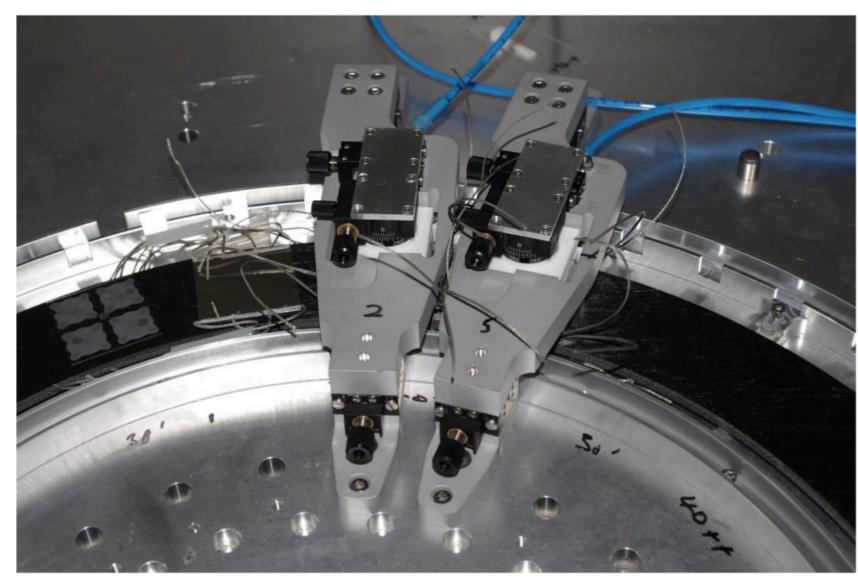
Manual bridges with manual micrometric xyz-theta adjustments

Needed custom made baseplate

No need to wait for glue curing between two modules.

Build a working UK Half-Ring 0 Now building UK Half-Ring 1

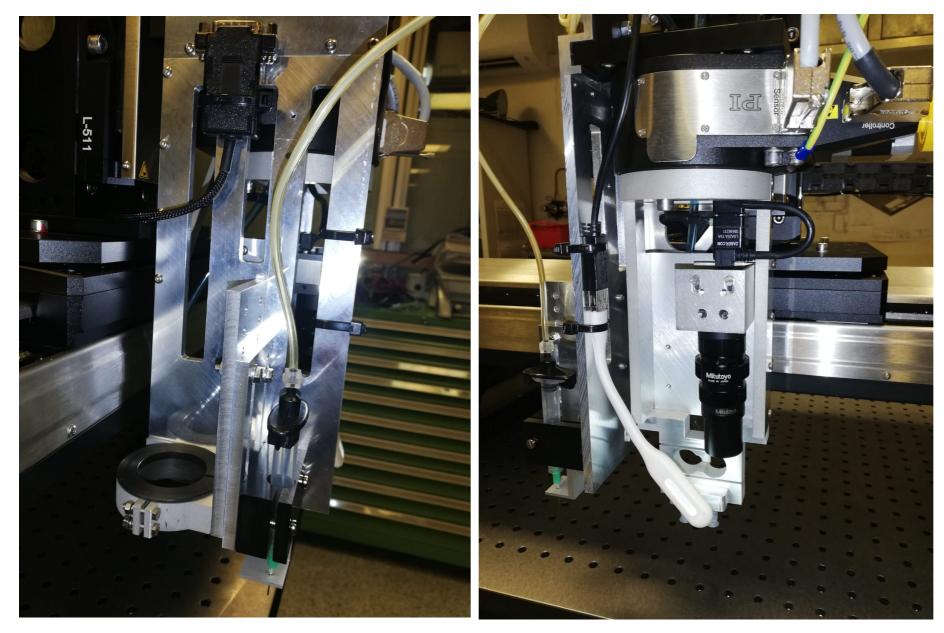
# Four loading sites: Oxford



Gantry X,Y,Z,Theta Automatic Bridges Needed custom made baseplate No need to wait for glue curing between two modules.

**Just started** 

# Four loading sites: Genova



#### **Gantry X,Y,Z,Theta**

Pick&Place head with microscope independent z-movements (supervised module after pick)

No need custom made baseplate

Need to wait for glue curing between two modules.

**Just started** 

## Four loading sites: Lecce vs Genova

#### GE Gantry X,Y,Z,Theta

Pick&Place head with microscope independent z-movements (supervised module after pick)

No need custom made baseplate

Need to wait for glue curing between two modules.

**Just started** 

LE Gantry X,Y,Z,Theta

**Pick&Place head** 

Microscope on z stage (no supervised module after pick)

No need custom made baseplate

Need to wait for glue curing between two modules.

Hardware and software (Labview + Original) capable to due a large scale loading exercise.

## Glue thickness and chip coverage

The most crucial step it is the final glue thickness and chip coverage.

It is related to:

-Deposited glue quantity (assuming good spread when loading)

- -Module planarity
- -Half-ring local support local planarity

-Relative orientation in space of module chip surface and half ring during loading

**Strategy to deal with** 

- -RAL : pillars and silicon spheres (already tried)
- -OXFORD : silicon sphere (already tried) and
- -GENOVA : Strain Gauge on Pick&Place head (to be proven)
- -LECCE : Geometrical plane adjustment of (parking tool ?) and pick and place head to be parallel to the half-ring (our next goal)